



## Material Content Data Sheet



<b>Sales Product Name</b>				IPC100N04S5L-1R1		<b>Issued</b>		25. January 2018	
<b>MA#</b>				MA001312756					
<b>Package</b>				PG-TDSON-8-34		<b>Weight*</b>		113.50 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	2.124	1.87	1.87	18715	18715	
leadframe	non noble metal	iron	7439-89-6	0.053	0.05		469		
	inorganic material	phosphorus	7723-14-0	0.016	0.01		141		
	non noble metal	copper	7440-50-8	53.151	46.84	46.90	468282	468892	
wire	noble metal	gold	7440-57-5	0.042	0.04	0.04	370	370	
encapsulation	organic material	carbon black	1333-86-4	0.073	0.06		644		
	plastics	epoxy resin	-	5.775	5.09		50877		
	inorganic material	silicondioxide	60676-86-0	30.701	27.05	32.20	270486	322007	
leadfinish	non noble metal	tin	7440-31-5	1.574	1.39	1.39	13866	13866	
plating	noble metal	silver	7440-22-4	0.209	0.18	0.18	1843	1843	
solder	noble metal	silver	7440-22-4	0.057	0.05		506		
	non noble metal	tin	7440-31-5	0.046	0.04		405		
	non noble metal	lead	7439-92-1	2.192	1.93	2.02	19316	20227	
CLIP plating	noble metal	silver	7440-22-4	0.639	0.56	0.56	5630	5630	
heat sink CLIP	non noble metal	iron	7439-89-6	0.017	0.01		148		
	inorganic material	phosphorus	7723-14-0	0.005	0.00		45		
	non noble metal	copper	7440-50-8	16.828	14.83	14.84	148257	148450	
*deviation	< 10%					Sum in total:	100.00	1000000	

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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